

Product  
Bulletin

# U107

Excellent for potting and encapsulation of electronic modules, coils, and micro-electronic networks that require thermal cycling extremes and low pressure on delicate components.

**GENERAL DESCRIPTION**

U107 offers the most advanced technology in urethane rubber encapsulating systems.

Maximum physical, thermal, and electrical properties are the outstanding features along with long working pot life and low viscosity for easy pouring.

U107 has high adhesion to most surfaces, low exotherm, low internal stress and minimal shrinkage during polymerization.

U107 is excellent for potting and encapsulating electronic modules, coils and micro-electronic networks that require thermal cycling extremes and low pressure on delicate components.

U107 is available in sample kits for evaluation and is in stock in various container sizes.

**SPECIFICATIONS**
HANDLING CHARACTERISTICS

Mix Ratio, Catalyst to Resin, by Weight:	2:5
Workable Pot Life, 100 g @ 25°C:	45 min.
Mixed Viscosity @ 25°C cps:	5,500
Recommended Cure:	24 hrs. @ room temp.
Color:	Off white

PHYSICAL CHARACTERISTICS

Shrinkage Linear, in / in:	0.001
Hardness, Shore A:	85
Specific Gravity, 25°C:	1.26
Tensile Strength, psi:	1,172
Compressive Strength, psi:	30

THERMAL CHARACTERISTICS

Thermal Conductivity, btu / hr / ft <sup>2</sup> / °F / in:	2.9
Heat Distortion, °C:	85
Operating Temperature Range, °C:	-50 to +125

ELECTRICAL CHARACTERISTICS

Dielectric Strength, volts / mil:	590
Dielectric Constant, 60 Hz:	2.94
Dissipation Factor, 60 Hz:	0.0310
Volume Resistivity, ohm · cm:	1.1 x 10 <sup>16</sup>